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FQP18N20V2/FQPF18N20V2

200V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, high efficiency switching for DC/DC converters, and DC motor control.

Features

- 18A, 200V, $R_{DS(on)} = 0.14\Omega @V_{GS} = 10 V$
- Low gate charge (typical 20 nC)
- Low Crss (typical 25 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		FQP18N20V2	FQPF18N20V2	Units
V _{DSS}	Drain-Source Voltage		200		V
I _D	Drain Current - Continuous (T _C = 25°C)		18	18	Α
	- Continuous (T _C = 100°C	C)	11.9	11.9	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	72	72	Α
V _{GSS}	Gate-Source Voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		340		mJ
I _{AR}	Avalanche Current	(Note 1)		18	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		12.3		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		(6.5	V/ns
P_D	Power Dissipation (T _C = 25°C)		123	40	W
	- Derate above 25°C		0.99	0.32	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300		°C

Thermal Characteristics

Symbol	Parameter	FQP18N20V2	FQPF18N20V2	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.01	3.1	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
ΔBV_{DSS} / $\Delta T_{,l}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		0.25		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 160 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 9 A		0.12	0.14	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_D = 9 \text{ A}$ (Note 4)		11		S
Dvnami	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		830	1080	pF
C _{oss}	Output Capacitance			200	260	pF
C _{rss}	Reverse Transfer Capacitance			25	33	pF
C _{oss}	Output Capacitance	V _{DS} = 160 V, V _{GS} = 0 V, f = 1.0 MHz		70		pF
C _{oss} eff.	Effective Output Capacitance	$V_{DS} = 0V \text{ to } 160 \text{ V}, V_{GS} = 0 \text{ V}$		135		pF
Switchi	ing Characteristics		•			
t _{d(on)}	Turn-On Delay Time		T	16	40	ns
t _r	Turn-On Rise Time	$V_{DD} = 100 \text{ V}, I_D = 18 \text{ A},$		133	275	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$		38	85	ns
t _f	Turn-Off Fall Time	(Note 4, 5		62	135	ns
Q _g	Total Gate Charge	V _{DS} = 160 V, I _D = 18 A,		20	26	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 100 \text{ V}, I_D = 10 \text{ A},$ $V_{GS} = 10 \text{ V}$		5.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		10		nC
	Course Diede Cherenterieties er	ad Mayimum Datinga				
Drain-S	Source Diode Characteristics as Maximum Continuous Drain-Source Did				18	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F				72	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 18 A			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 18 \text{ A,}$		158		ns
Q _{rr}	,	$dI_{F}/dt = 100 \text{ A}/\mu\text{s} \qquad \text{(Note 4)}$				

- $\label{eq:Notes:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ \textbf{1.} & \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ \textbf{2.} & \textbf{L} = \textbf{1.58mH, } \textbf{I}_{AS} = \textbf{18A, } \textbf{V}_{DD} = \textbf{50V, } \textbf{R}_{G} = \textbf{25} \ \Omega, \textbf{Starting } \ \textbf{T}_{J} = \textbf{25}^{\circ} \textbf{C} \\ \textbf{3.} & \textbf{I}_{SD} \leq \textbf{18A, } \textbf{di/dt} \leq 200\textbf{A/\mus, } \textbf{V}_{DD} \leq \textbf{BV}_{DSS,} \textbf{Starting } \ \textbf{T}_{J} = \textbf{25}^{\circ} \textbf{C} \\ \textbf{4.} & \textbf{Pulse Test: Pulse width} \leq \textbf{300} \mu \textbf{s, Duty cycle} \leq \textbf{2\%} \\ \textbf{5.} & \textbf{Essentially independent of operating temperature} \\ \end{tabular}$

Typical Characteristics

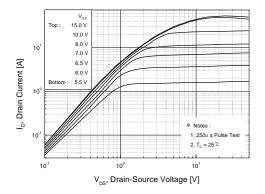


Figure 1. On-Region Characteristics

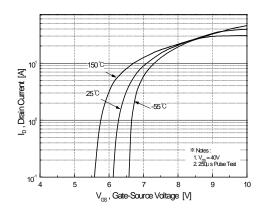


Figure 2. Transfer Characteristics

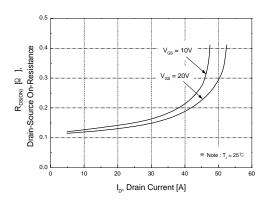


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

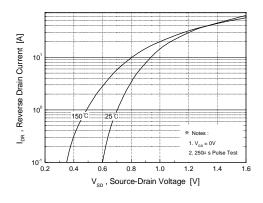


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

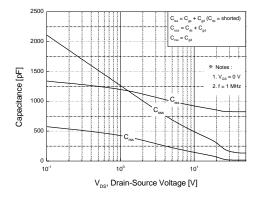


Figure 5. Capacitance Characteristics

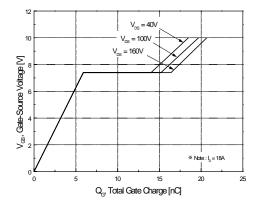
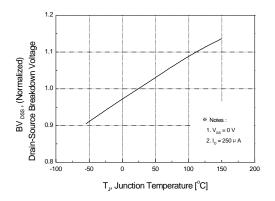


Figure 6. Gate Charge Characteristics

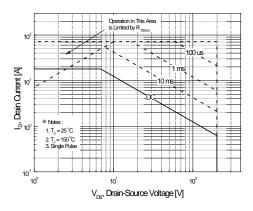
Typical Characteristics (Continued)



3.0 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 2.5 () 3.5 () 3.5 () 3.5 () 3.5 () 4.5 () 3.5 () 4.5 () 4.5 () 5.5 () 5.5 () 6

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation



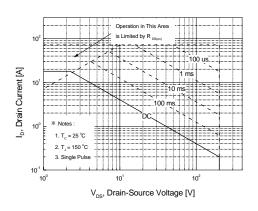


Figure 9-1. Maximum Safe Operating Area for FQP18N20V2

Figure 9-2. Maxiumum Safe Operating Area for FQPF18N20V2

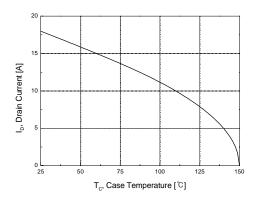


Figure 10. Maximum Drain Current vs. Case Temperature

Typical Characteristics (Continued)

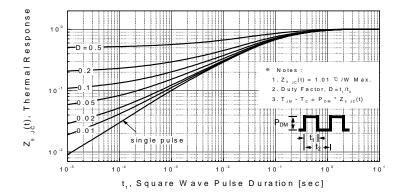


Figure 11-1. Transient Thermal Response Curve for FQP18N20V2

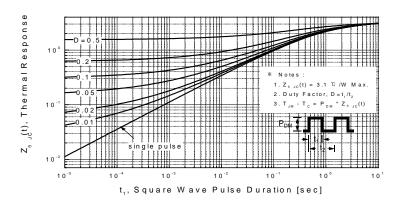
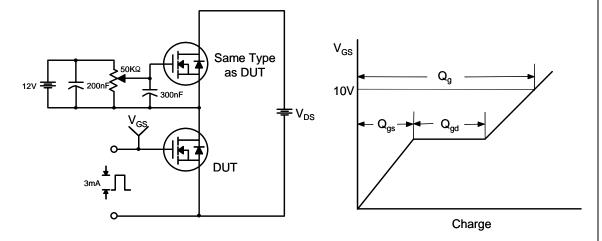
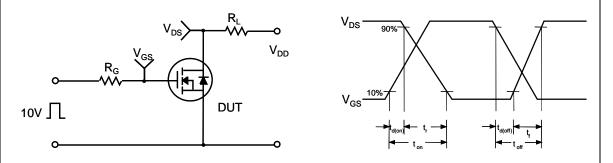


Figure 11-2. Transient Thermal Response Curve for FQPF18N20V2

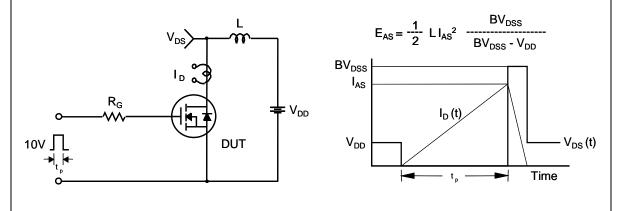
Gate Charge Test Circuit & Waveform



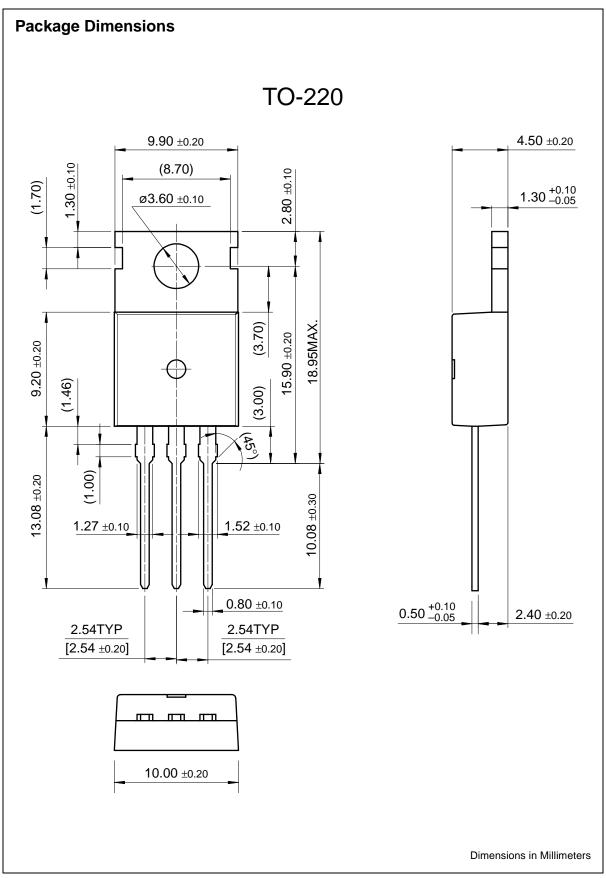
Resistive Switching Test Circuit & Waveforms

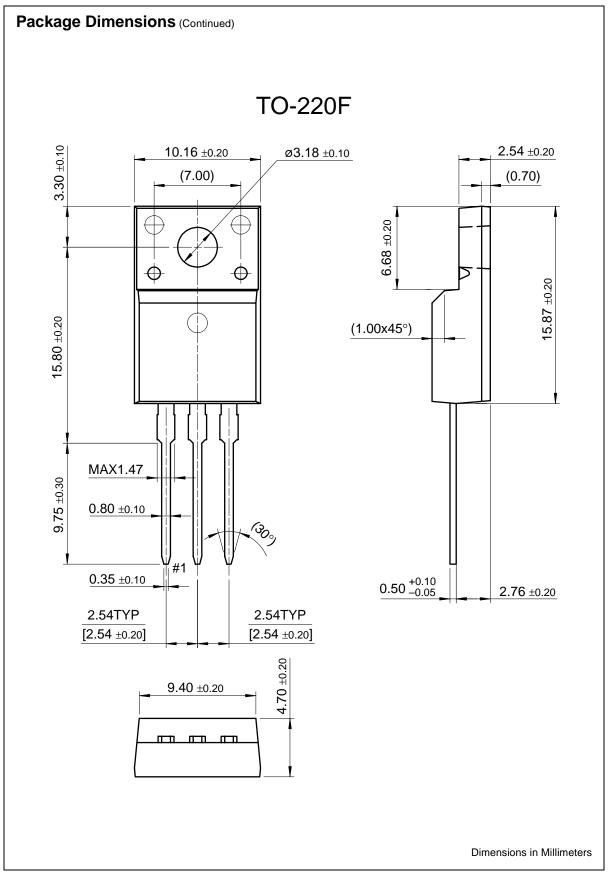


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT I_{SD o} Driver Same Type as DUT V_{DD} • dv/dt controlled by R_G • I_{SD} controlled by pulse period Gate Pulse Width V_{GS} Gate Pulse Period 10V (Driver) I_{FM} , Body Diode Forward Current \mathbf{I}_{SD} di/dt (DUT) I_{RM} **Body Diode Reverse Current** V_{DS} (DUT) Body Diode Recovery dv/dt **Body Diode** Forward Voltage Drop





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